



PRODUCT DESCRIPTION

Tputty™ 607MF is a high thermally conductive single part dispensable gap filler specially designed to response to today's need for high-speed assembly. It's 105 g/min flow rate benefits engineers seeking productivity improvement within assembly operations. With 6.2 W/m·K thermal conductivity and high reliability, Tputty 607MF is an ideal solution for various applications. Tputty™ 607MF is a soft, compliant, high flow rate dispensable gap filler providing low thermal resistance and high reliability.

FEATURES AND BENEFITS

- 6.2 W/m-K thermal conductivity
- High flow rate and good tackiness
- Easily reworkable
- Demonstrated thermal cycling stability
- Meets ROHS and REACH requirements

APPLICATIONS

- Telecom base stations
- Graphic chips
- Microprocessors
- High-power automotive electronic controls

MAIN PROPERTIES

TYPICAL PROPERTIES	VALUE	TEST METHOD
Composition	Ceramic filled dispensable silicone	
Color	Blue	Visual
Thermal Conductivity	6.2W/m-K	Hot Disk
Flow rate (75cc taper tip, 90psi)	105 g/min	Laird Method
Shelf Life	9 months	Laird Method
Density	3.42 g/cc	Helium Pycnometer
Minimum Bond Line Thickness	150 µm	Laird Method
Operating Temperature Range	-40°C to 200°C	
UL Flammability Rating	V-0	UL 94
Dielectric Breakdown Voltage	6kV/mm	ASTM D149
Outgassing TML (Weight%)	TBD	ASTM E595
Volume Resistivity	10 ¹⁴ ohm-cm	ASTM D257

PACKAGING

PACKAGING SIZE	FILL VOLUME	FILL WEIGHT
30cc syringe	30cc	103g
75cc cartridge	56cc	192g
180cc cartridge	159cc	544g
360cc cartridge	326cc	1115g
600cc cartridge	601cc	2055g
1 gallon pail	4060cc	13kg
5 gallon pail	5800cc	20kg

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THR-DS-Tputty 607MF

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